**ChipEx2017 – Call for Paper Submission Form**

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| Web Site: | Company Name: | LOGO (optional) |
| Email: | Mobile number: | Presenter Name: |
|  | Presentation title: | Mark **BOLD** your main Topic:   * Silicon solutions optimized for the next generation of application (e.g. automotive, high- performance systems, IoT, etc.) * Power Management & Signal Integrity * Analog Design, RF and Sensors * Physical Design and manufacturability * Intellectual Property for SoC & NoC * Verification, Simulation and Testing * Post Silicon and Reliability (including HW testing and packaging) * Emerging and creative design technologies * Users Track – bringing user experience to the public |
| Company Profile (up to 5 lines): | | |
| The Problem/Market need Addressed (up to 5 lines): | | |
| The innovative technology you wish to present – please elaborate (up to 10 lines): | | |
| Why do you consider it to be new and interesting (up to 5 lines): | | |
| Was this paper previously published or simultaneously under review by another conference: | | |
| Anything else you would like to add: | | |